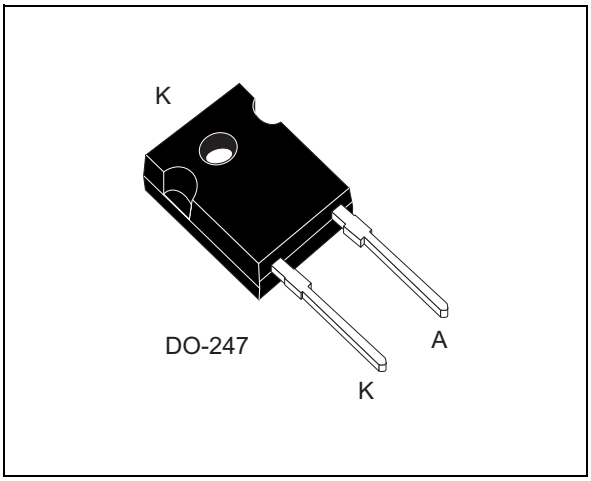
STTH30S12

Turbo 2 ultrafast high voltage rectifier

Datasheet – production data



Description

The STTH30S12 is developed using ST's Turbo 2 1200 V technology. It is well-suited as a boost diode, especially for use in UPS.

Table 1. Device summary

Symbol	Value
$I_{F(AV)}$	30 A
V_{RRM}	1200 V
t_{rr} (typ)	35 ns
V_F (typ)	1.9 V
T_j (max)	175 °C

Features

- Ultrafast switching
- Low reverse current
- Low thermal resistance
- Reduces switching and conduction losses

This is information on a product in full production. www.st.com

1 Characteristics

Table 2. Absolute ratings (limiting values at T_j = 25 °C, unless otherwise specified)

Symbol	Parameter		Value	Unit
V_{RRM}	Repetitive peak reverse voltage		1200	V
$I_{F(RMS)}$	Forward rms current		50	A
$I_{F(AV)}$	Average forward current, δ = 0.5	T_c = 70 °C	30	A
I_{FSM}	Surge non repetitive forward current	t_p = 10 ms sinusoidal	180	A
T_{stg}	Storage temperature range		-65 to +175	°C
T_j	Maximum operating junction temperature		175	°C

Table 3. Thermal parameters

Symbol	Parameter	Value	Unit
$R_{th(j-c)}$	Junction to case	0.95	°C/W

Table 4. Static electrical characteristics

Symbol	Parameter	Test conditions		Min.	Typ.	Max.	Unit
I_R (1)	Reverse leakage current	T_j = 25 °C	$V_R = V_{RRM}$			15	µA
		T_j = 150 °C			60	600	
V_F (2)	Forward voltage drop	T_j = 25 °C	I_F = 30 A		2.9		V
		T_j = 150 °C			1.9	2.7	

1. Pulse test: t_p = 5 ms, δ < 2%
2. Pulse test: t_p = 380 µs, δ < 2%

To evaluate the conduction losses use the following equation:

$P = 1.8 \times I_{F(AV)} + 0.03\ I_F{}^2{}_{(RMS)}$

Table 5. Dynamic characteristics

Symbol	Parameter	Test conditions		Min.	Typ.	Max.	Unit
t_{rr}	Reverse recovery time	T_j = 25 °C	I_F = 1 A, V_R = 30 V, dI_F/dt = 200 A/µs		35	50	ns
I_{RM}	Reverse recovery current	T_j = 125 °C	I_F = 30 A, V_R = 600 V, dI_F/dt = 200 A/µs		17	24	A
S	Softness factor				2		
Q_{RR}	Reverse recovery charge				2900		nC

Figure 1. Average forward power dissipation versus average forward current

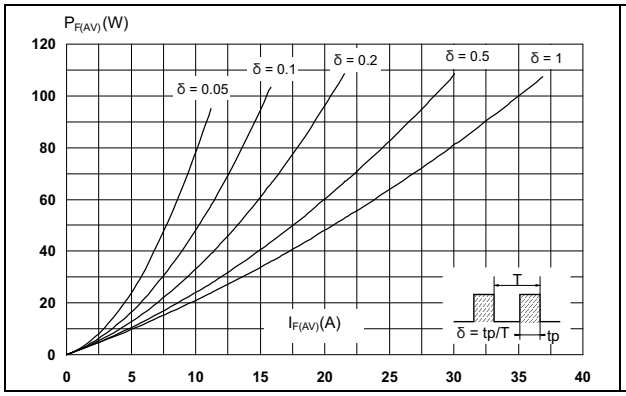


Figure 2. Forward voltage drop versus forward current (typical values)

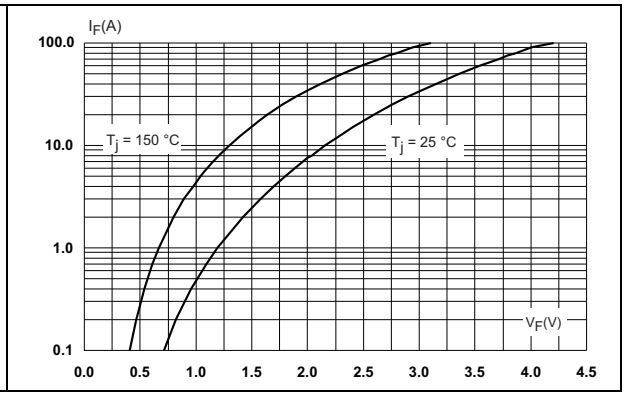


Figure 3. Forward voltage drop versus forward current (maximum values)

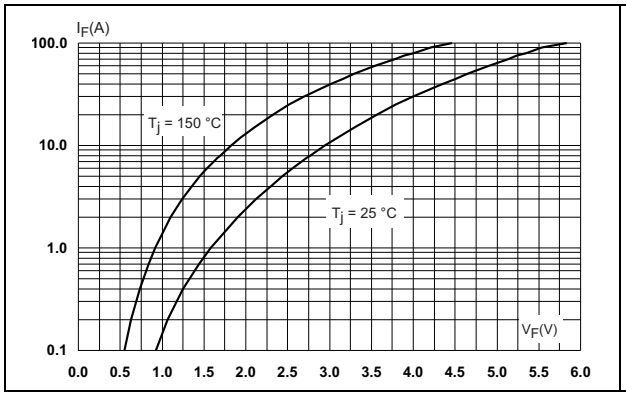


Figure 4. Relative variation of thermal impedance, junction to case, versus pulse duration

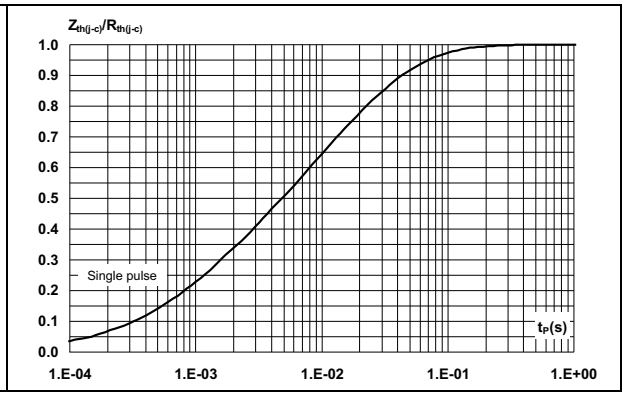


Figure 5. Peak reverse recovery current versus dI_F/dt (typical values)

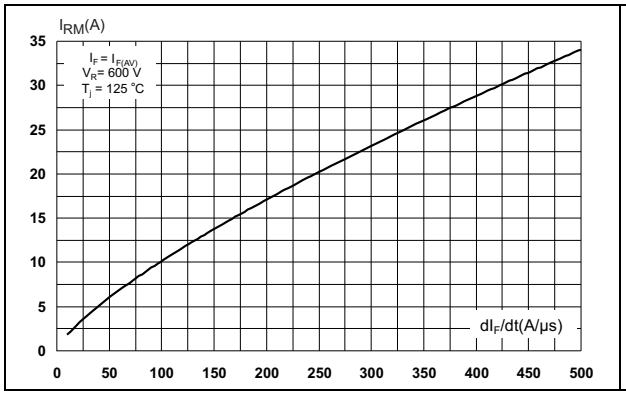


Figure 6. Reverse recovery time versus dI_F/dt (typical values)

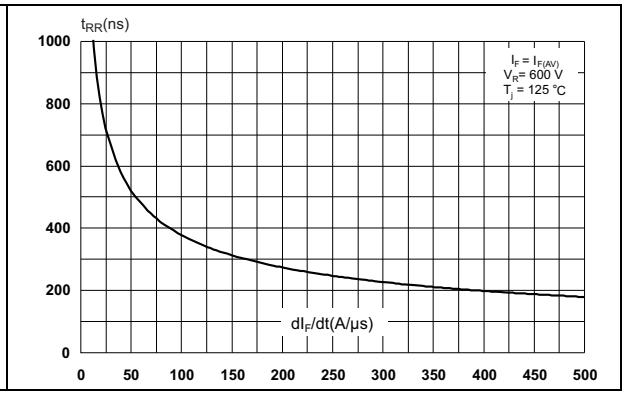


Figure 7. Reverse recovery charges versus dI_F/dt (typical values)

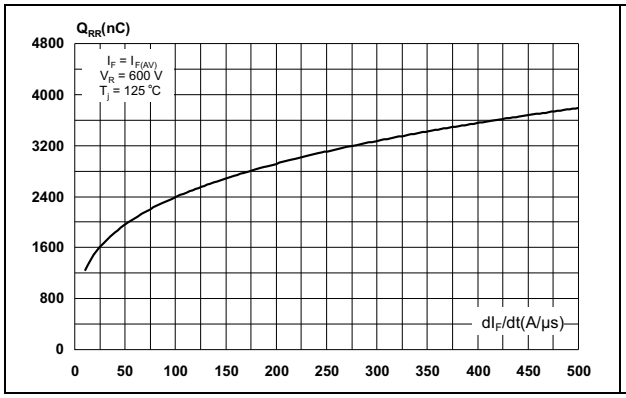


Figure 8. Reverse recovery softness factor versus dI_F/dt (typical values)

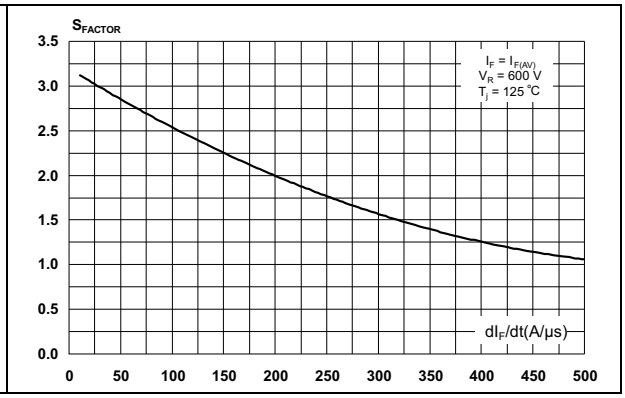


Figure 9. Relative variations of dynamic parameters versus junction temperature

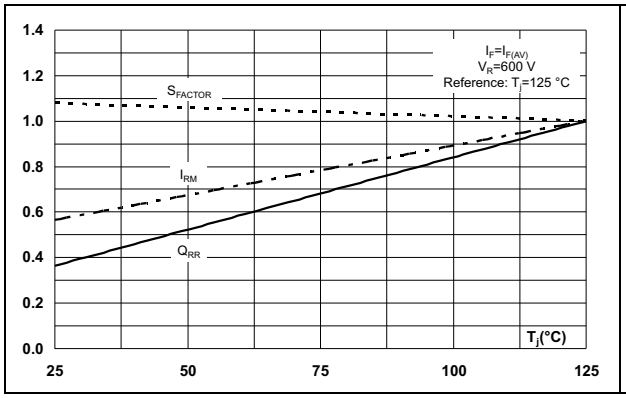
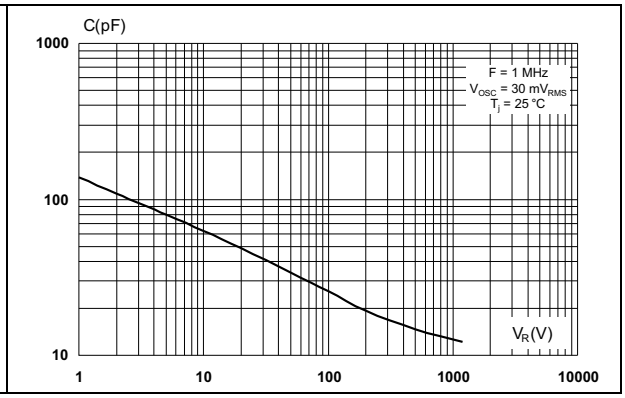


Figure 10. Junction capacitance versus reverse voltage applied (typical values)



2 Package information

- Epoxy meets UL94, V0
- Cooling method: by conduction (C)
- Recommended torque value: 0.4 N·m to 0.6 N·m

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: *www.st.com*. ECOPACK® is an ST trademark.

Figure 11. DO-247 dimension definitions

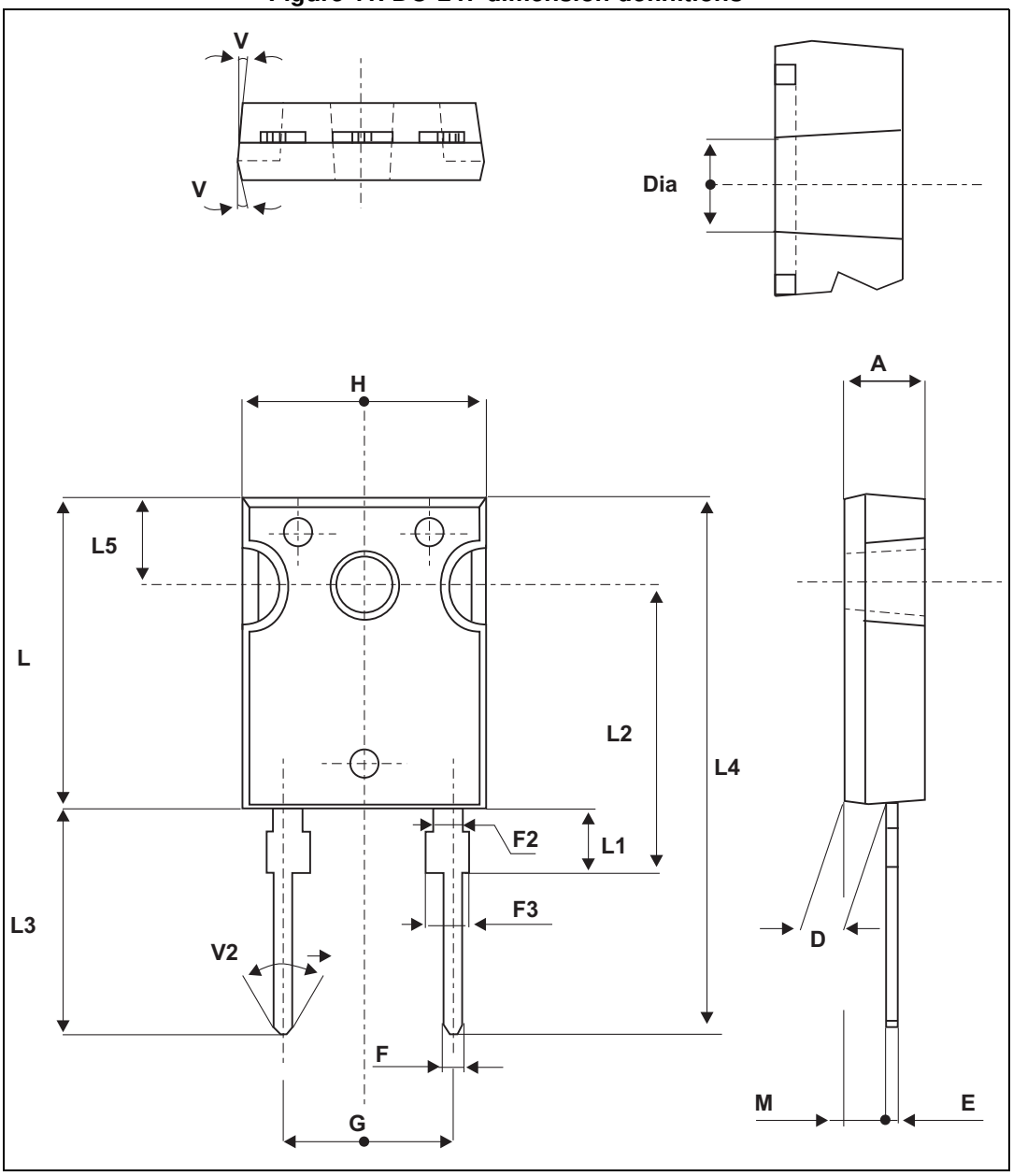


Table 6. DO-247 dimension values

Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	4.85		5.15	0.191		0.203
D	2.20		2.60	0.086		0.102
E	0.40		0.80	0.015		0.031
F	1.00		1.40	0.039		0.055
F2		2.00			0.078	
F3	2.00		2.40	0.078		0.094
G		10.90			0.429	
H	15.45		15.75	0.608		0.620
L	19.85		20.15	0.781		0.793
L1	3.70		4.30	0.145		0.169
L2		18.50			0.728	
L3	14.20		14.80	0.559		0.582
L4		34.60			1.362	
L5		5.50			0.216	
M	2.00		3.00	0.078		0.118
V		5°			5°	
V2		60°			60°	
Dia.	3.55		3.65	0.139		0.143

3 Ordering information

Table 7. Ordering information

Order code	Marking	Package	Weight	Base qty	Delivery mode
STTH30S12W	STTH30S12W	DO-247	4.46 g	50	Tube

4 Revision history

Table 8. Document revision history

Date	Revision	Changes
18-Sep-2014	1	Initial release

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